1. Record Nr. UNINA9911015970103321

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Titolo	Electronic Materials Innovations and Reliability in Advanced Memory Packaging / / by Chong Leong Gan, Chen Yu Huang
Pubbl/distr/stampa	Cham : , : Springer Nature Switzerland : , : Imprint : Springer, , 2025
ISBN	3-031-94795-9
Edizione	[1st ed. 2025.]
Descrizione fisica	1 online resource (278 pages)
Collana	Springer Series in Reliability Engineering, , 2196-999X
Altri autori (Persone)	HuangChen-Yu
Disciplina	541.0421 621.3815
Soggetti	Electronics - Materials Electronic circuits Electronic circuit design Materials Industrial engineering Production engineering Electronic Materials Electronic Circuits and Systems Electronics Design and Verification Materials Engineering Industrial and Production Engineering
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Nota di contenuto	Influences of Electronic Materials Properties on Packaging Reliability -- Mechanical and Thermal Stress of Encapsulant and New Materials in Memory Packaging -- Materials Development for Future Data Center Applications -- Advanced Chiplets and Heterogenous Integration in Memory Device Packaging -- Hybrid Bonding Device Packaging -- Hardware Reliability for Memory Modules and SSDs -- Innovative Sustainable Electronics Materials in Advanced Memory Packaging -- PCB and Substrate in Future Memory Applications.
Sommario/riassunto	This book provides a comprehensive introduction the reliability, and electronic materials innovations in advanced memory device packaging from component to system level. Special features of this book are

sections covering not only the advanced packaging materials, but also system level packaging and integration in memory modules and solid state drives (SSD). The book is an extremely useful and applicable guide to professionals and students on materials reliability in memory device packaging - from component to system level.